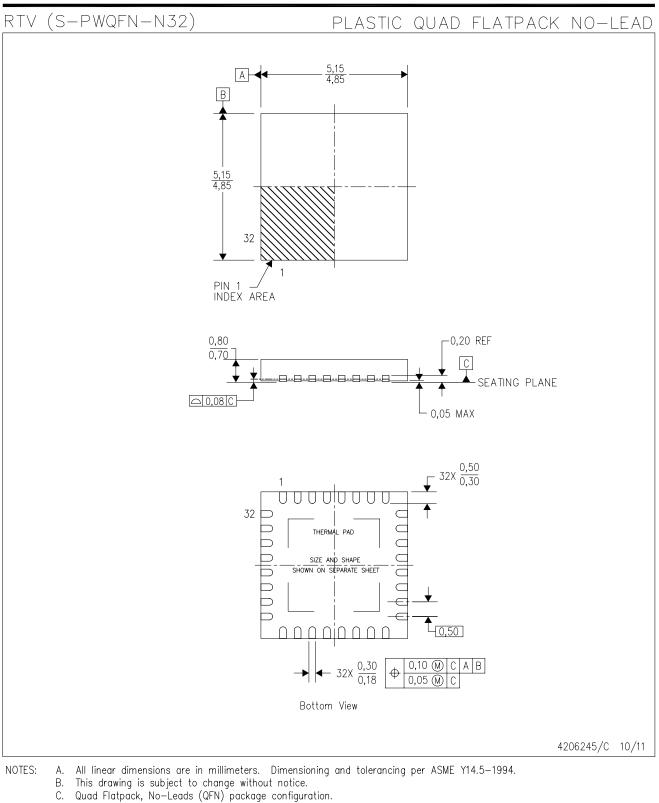
MECHANICAL DATA



- D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 F. Falls within JEDEC MO-220.



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